

sub B

What is claimed is:

1. An SAW filter device with a chip substrate of a piezoelectric material having a plurality of interdigital transducers and accommodated in a plastic package, wherein a common potential means for providing a common potential in the interdigital transducers, a charge neutralizing means for neutralizing charge generated on the chip substrate due to polarization, or a charge escape means for causing escape of charge generated on the chip substrate due to polarization, is provided as an electric discharge preventing means for preventing electric discharge among the plurality of interdigital transducers on the chip substrate.

2. The SAW filter device according to claim 1, wherein the electric discharge preventing means is realized by a high resistivity thin film provided between the chip substrate and the interdigital transducers and covering the front surface of the chip substrate.

3. The SAW filter device according to claim 1, wherein the electric discharge preventing means is realized by a high resistivity thin film formed such as to cover the entire interdigital transducer.

sub A

4. The SAW filter device, which further comprises a film of a conductive material covering the front surface of the chip substrate and the interdigital transducers.

*sub
B6*

5. The SAW filter device according to claim 1, wherein the electric discharge preventing mean is realized by a film of a conductive material provided ^{on} a front surface side edge portion of the chip substrate.

6. The SAW filter device according to claim 1, wherein the electric discharge preventing means is realized by a film of a conductive material provided on the front surface side edge portion of the chip substrate.

*Ans 660
MAY 11 1981
RECORDED
1070*

7. The SAW filter device according to claim 1, wherein the electric discharge prevention means is realized by a high resistivity pattern provided such as to surround a front surface side edge portion of the chip substrate.

8. An SAW filter device with a chip substrate of a piezoelectric material having a plurality of interdigital transducers and accommodated in a plastic package, wherein a first pattern as ^{an} extension of part of the interdigital transducers, a second pattern spaced apart from the first pattern and a dummy electrode pattern connected to the second pattern are formed on the front surface of the chip substrate as the ^{an} electric discharge preventing means for preventing electric discharge among the plurality of interdigital electric patterns.

9. An SAW filter device with a chip substrate of

*Concl'd
B'*

a piezoelectric material having a plurality of interdigital transducers and accommodated in a plastic package, ^{an} wherein the electric discharge preventing means for preventing electric discharge among the plurality of interdigital electric patterns is realized by opposed portions of the interdigital transducers having non-sharp shapes.

10. A package for accommodating an SAW filter in the inside, which comprises a terminal member made of a metal extending out of the package and extending into the package such as to form an L-shaped portion.

11. An SAW filter device including an SAW filter according to one of claims 1 to 9, which comprises a plastic package including a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

12. The SAW filter device according to claim 11, wherein the back surface of the chip substrate is secured by a conductive adhesive to the package.

